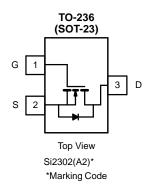
B-Channel 1.25-W, 2.5-V MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	$r_{DS(on)}\left(\Omega\right)$	I _D (A)	
20	0.040 @ V _{GS} = 4.5 V	3.0	
	0.060 @ V _{GS} = 2.5 V	2.0	



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V_{GS}	±8	·	
Continuous Drain Current (T _J = 150°C) ^b	T _A = 25°C	ID	3.0		
Pulsed Drain Current ^a		I _{DM}	10	^	
Continuous Source Current (Diode Conduction) ^b		I _S	1.6		
Power Dissipation ^b	T _A = 25°C	P _D	1.25	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Maximum Junction-to-Ambient ^b	D	100	°C/W	
Maximum Junction-to-Ambient ^c	R _{thJA}	166	*C/VV	

Notes

- Pulse width limited by maximum junction temperature. Surface Mounted on FR4 Board, $t \le 5$ sec.
- Surface Mounted on FR4 Board.



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Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static			•	•	•		
Drain-Source Breakdown Voltage	V(_{BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			_ v	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.5		1.0		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS} —	V _{DS} = 16 V, V _{GS} = 0 V			50	nA	
		$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$					
On-State Drain Current ^a		$V_{DS} \ge 5 V$, $V_{GS} = 4.5 V$	6				
	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 2.5 \text{ V}$	4			A	
Drain-Source On-Resistance ^a		$V_{GS} = 4.5 \text{ V}, I_D = 3.0 \text{ A}$			0.040		
	r _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 2.0 \text{ A}$			0.060	Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 5 \text{ V, } I_D = 3.0 \text{ A}$		10		S	
Diode Forward Voltage	V _{SD}	$I_S = 1.0 \text{ A}, V_{GS} = 0 \text{ V}$			1.28	٧	
Dynamic			•				
Total Gate Charge	Qg			5.4	10	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.6 \text{ A}$		0.65			
Gate-Drain Charge	Q_{gd}			1.60			
Input Capacitance	C _{iss}			340		pF	
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		115			
Reverse Transfer Capacitance	C _{rss}			33			
Switching			•				
Turn-On Delay Time	t _{d(on)}	V_{DD} = 10 V, R_L = 5.5 Ω $I_D \cong 3.6$ A, V_{GEN} = 4.5 V, R_G = 6 Ω		12	25	ns	
Rise Time	t _r			36	60		
Turn-Off Delay Time	t _{d(off)}			34	60		
Fall-Time	t _f			10	25		

Notes a. Pulse test: PW \leq 300 μ s duty cycle \leq 2%..

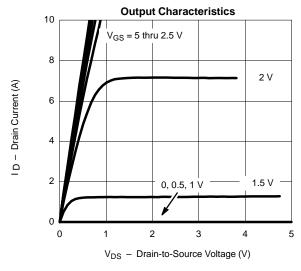
VNLR02

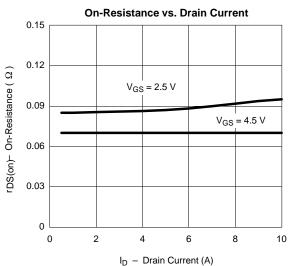


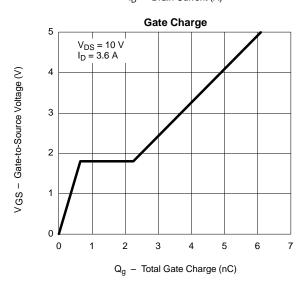
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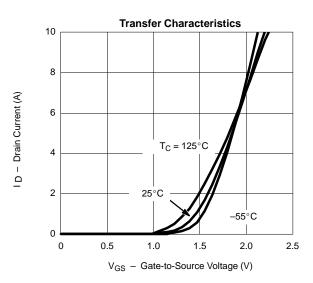
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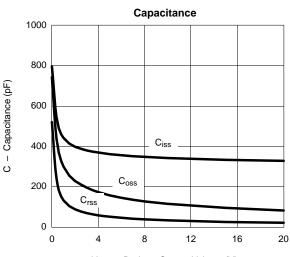
TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

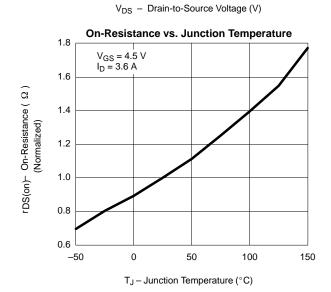










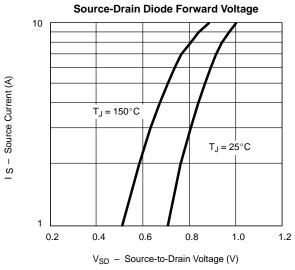


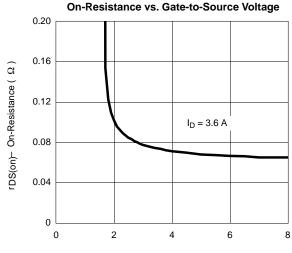


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TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)





V_{GS} – Gate-to-Source Voltage (V)

